

Fuseholder Open Design, 5 x 20 mm, SMD, var. Covers, IEC 60335-1



250 VAC · 4 W / 10 A (VDE) · 500 VAC/DC · 10 A (UL/CSA)

**Description**

- Meets the new requirements of IEC 60335-1 Ed. 4.0 for appliances in unattended use (clause 30.2.3). This includes the enhanced requirements of glow wire tests acc. to IEC 60695-2-11 to -13. Order number: 0031.8263-5 / 0031.8273-5
- Low profile fuse block with insulation walls

**Standards**

- IEC 60127-6
- UL 4248-1 / UL 512
- CSA C22.2 no. 39

**Approvals**

- VDE License Number: 40001042
- UL File Number: E39328

**Applications**

- Industrial electronic
- Household appliances

**References**

[General Product Information](#)  
[Packaging Details](#)

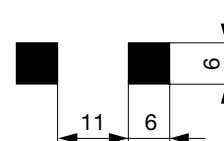
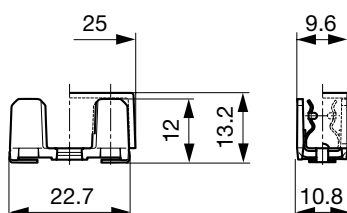
**Weblinks**

[Approvals, RoHS, CHINA-RoHS, e-Store, Distributor-Stock-Check, Accessories, Product Change Notification \(PCN\)](#)

**Technical Data**

Fuse-Link	5 x 20 mm
Mounting	PCB
Terminal	Solder SMT
Rated Voltage	250 VAC (VDE), 500 VAC/DC (UL/CSA)
Rated Current	10 A (VDE), 10 A (UL/CSA)
Rated Power Acceptance IEC	4 W / 10 A @ Ta 23 °C 2.5 W / 10 A with transparent cover, see derating curves
Degree of Protection	IP 00 / IP 20
Protection Class	Suitable for appliances with protection class 1 or 2 acc. to IEC 61140
Admissible Ambient Air Temp.	-40 °C to 85 °C
Climatic Category	40/085/21 acc. to IEC 60068-1
Material: Socket	see variants
Material: Terminals	Tin-Plated Copper Alloy
Unit Weight (Socket/Cap)	1.7 g
Storage Conditions	0 °C to 60 °C, max. 70% r.h.
Product Marking	 Type, Voltage, Power Acc./Current Rating, Approvals

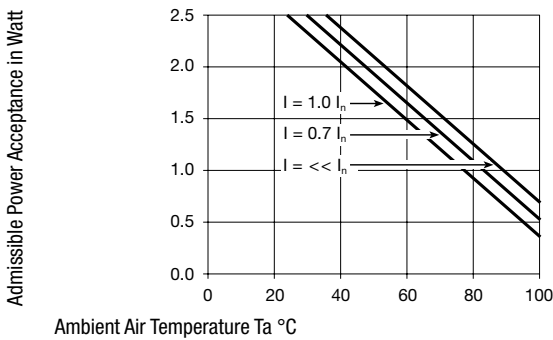
Soldering Methods	Reflow (see variants)
Solderability	245 °C / 3 sec acc. to IEC 60068-2-58, Test Td
Resistance to Soldering Heat	240 - 260 °C / 20 - 40 sec acc. to IPC/ JEDEC J-STD-020D
Contact Resistance	< 5 mΩ at 20 mV
Dielectric Strength	> 3 kV between L-N (50 Hz; 1 min)
Impulse Withstand Voltage	> 4 kV between L-N
Insulation Resistance	> 10 MΩ between L-N (500 VDC; 1 min)
Overvoltage Category	I - III acc. to IEC 60664-1
Pollution Degree	1 - 3 acc. to IEC 60664-1
Resistance to Vibration	acc. to IEC 60068-2-6, test Fc

**Abmessungen**
 22.7 mm


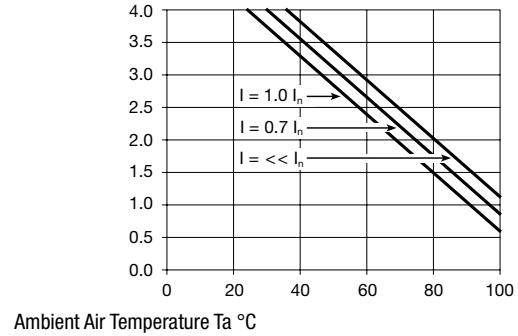
Soldering pads

### Derating Curves for Fuseholders

With Transparent Cover



Admissible Power Acceptance in Watt



### Variants

Holder	Material	Material: Terminals	Reflow Condition	Packaging	Order Number
●	Thermoplastic	Tin-Plated Copper Alloy	(acc. to JEDEC J-STD-020C), T <sub>p</sub> =240 +0/-5 °C, t <sub>p</sub> = 20-40 s	Bulk 128 x 91 x 60 mm(100 pcs.)	0031.8221
●	Thermoplastic	Tin-Plated Copper Alloy	(acc. to JEDEC J-STD-020C), T <sub>p</sub> =240 +0/-5 °C, t <sub>p</sub> = 20-40 s	Blister Tape 38 cm Reel(400 pcs.)	0031.8225
●	Thermoplastic	Tin-Plated Copper Alloy	(acc. to JEDEC J-STD-020C), T <sub>p</sub> =240 +0/-5 °C, t <sub>p</sub> = 20-40 s	Blister Tray 266 x 173 mm(500 pcs.)	0031.8222
●	Spec. Thermoplastic 2	Tin-Plated Copper Alloy	acc. to JEDEC J-STD-020C, T <sub>p</sub> =260 +0/-5 °C, t <sub>p</sub> = 20-40 s	Bulk 128 x 91 x 60 mm(100 pcs.)	0031.8263
●	Spec. Thermoplastic 2	Tin-Plated Copper Alloy	acc. to JEDEC J-STD-020C, T <sub>p</sub> =260 +0/-5 °C, t <sub>p</sub> = 20-40 s	Blister Tape 38 cm Reel(400 pcs.)	0031.8265
●	Spec. Thermoplastic 2	Tin-Plated Copper Alloy	acc. to JEDEC J-STD-020C, T <sub>p</sub> =260 +0/-5 °C, t <sub>p</sub> = 20-40 s	Blister Tray 266 x 173 mm(500 pcs.)	0031.8264
●	Spec. Thermoplastic 2	Gold-Plated Copper Alloy	acc. to JEDEC J-STD-020C, T <sub>p</sub> =260 +0/-5 °C, t <sub>p</sub> = 20-40 s	Bulk 128 x 91 x 60 mm(100 pcs.)	0031.8273
●	Spec. Thermoplastic 2	Gold-Plated Copper Alloy	acc. to JEDEC J-STD-020C, T <sub>p</sub> =260 +0/-5 °C, t <sub>p</sub> = 20-40 s	Blister Tape 38 cm Reel(400 pcs.)	0031.8275
●	Spec. Thermoplastic 2	Gold-Plated Copper Alloy	acc. to JEDEC J-STD-020C, T <sub>p</sub> =260 +0/-5 °C, t <sub>p</sub> = 20-40 s	Blister Tray 266 x 173 mm(500 pcs.)	0031.8274

Spec. thermoplastic meet the new requirements of IEC 60335-1 Ed. 4.0 for appliances in unattended use (clause 30.2.3). This includes the enhanced requirements of glow wire tests acc. to IEC 60695-2-11 to -13.

0031.8273, 0031.8274 and 0031.8275 with gold-plated clips are more heat resistant than 0031.8263, 0031.8264 and 0031.8265 with tin-plated clips.

If reflow soldering problems with standard thermoplastic occur, it is recommended testing spec. thermoplastic 2 versions with tin-plated and gold-plated clips. If tin-plated version meets the requirement then this would be the right choice because of price.

**Packaging Unit** see variants

### Accessories

#### Description



**Covers OGN, OGN-SMD**  
Cover for Holder OGN, OGN-SMD

Transparent Cover	0853.0551
Reflow-Cover	0853.0571
Cover, black, meets IEC 60335-1 Ed. 4.0	0853.0575
Reflow-Cover with Clamp	0853.0576

**Carriage OGN, OGN-SMD**  
Fuse Carriage with Handle for OGN, OGN-SMD

black	0853.1201
white	0853.1202
blue	0853.1203
brown	0853.1204

## Order Numbers for Pre-Assembled OGN-SMD, Blister Tape Packaging with 400 pieces per reel

Rated current I <sub>n</sub>	FTT 5x20 Fuse With Reflow-Cover 0853.0571	FTT 5x20 Fuse No Cover	FST 5x20 Fuse With Reflow-Cover 0853.0571	FST 5x20 Fuse No Cover	FSF 5x20 Fuse With Reflow-Cover 0853.0571	FSF 5x20 Fuse No Cover
50 mA			0031.8304	0031.8354		
63 mA	0031.8501	0031.8551	0031.8305	0031.8355		
80 mA	0031.8502	0031.8552	0031.8306	0031.8356		
100 mA	0031.8503	0031.8553	0031.8307	0031.8357		
125 mA	0031.8504	0031.8554	0031.8308	0031.8358		
160 mA	0031.8505	0031.8555	0031.8309	0031.8359		
200 mA	0031.8506	0031.8556	0031.8310	0031.8360		
250 mA	0031.8507	0031.8557	0031.8311	0031.8361		
315 mA	0031.8508	0031.8558	0031.8312	0031.8362		
400 mA	0031.8509	0031.8559	0031.8313	0031.8363		
500 mA	0031.8510	0031.8560	0031.8314	0031.8364	0031.8413	0031.8463
630 mA	0031.8511	0031.8561	0031.8315	0031.8365	0031.8414	0031.8464
800 mA	0031.8512	0031.8562	0031.8316	0031.8366	0031.8415	0031.8465
1 A	0031.8513	0031.8563	0031.8317	0031.8367	0031.8416	0031.8466
1,25 A	0031.8514	0031.8564	0031.8318	0031.8368	0031.8417	0031.8467
1,6 A	0031.8515	0031.8565	0031.8319	0031.8369	0031.8418	0031.8468
2 A	0031.8516	0031.8566	0031.8320	0031.8370	0031.8419	0031.8469
2,5 A	0031.8517	0031.8567	0031.8321	0031.8371	0031.8420	0031.8470
3,15 A	0031.8518	0031.8568	0031.8322	0031.8372	0031.8421	0031.8471
4 A	0031.8519	0031.8569	0031.8323	0031.8373	0031.8422	0031.8472
5 A			0031.8324	0031.8374	0031.8423	0031.8473
6,3 A			0031.8325	0031.8375	0031.8424	0031.8474
8 A			0031.8326	0031.8376	0031.8425	0031.8475
10 A			0031.8327	0031.8377	0031.8426	0031.8476

## Данный компонент на территории Российской Федерации

### Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

### Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: [info@moschip.ru](mailto:info@moschip.ru)

Skype отдела продаж:

moschip.ru

moschip.ru\_4

moschip.ru\_6

moschip.ru\_9